



## Materials Declaration Form

<b>IPC Form Type *</b>	1752 Distribute	<b>Version</b>	2
<b>Sectionals *</b>	Material Info Manufacturing Info	<b>Subsectionals *</b>	A-D  * : Required Field

Supplier Information			
<b>Company Name *</b>	STMicroelectronics	<b>Response Date *</b>	23-06-2025
<b>Company Unique ID</b>	NL 008751171B01		
<b>Contact Name *</b>	Refer to Supplier Comment section		Refer to Supplier Comment section
<b>Contact Phone *</b>	Refer to Supplier Comment section	<b>Contact Email *</b>	Refer to Supplier Comment section
<b>Authorized Representative *</b>	MDG MD CHAMPION	<b>Representative Title</b>	MDG MD CHAMPION
<b>Representative Phone *</b>	Refer to Supplier Comment section	<b>Representative Email *</b>	Refer to Supplier Comment section
<b>Supplier Comment</b>	Online Technical Support - STMicroelectronics : <a href="http://www.st.com/web/en/support/support.html">http://www.st.com/web/en/support/support.html</a>		

**Uncertainty Statement**


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Legal Statement			
<b>Supplier Acceptance *</b>	true	<b>Legal Declaration *</b>	Standard

**Legal Statement**

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
ST25R501-HMWT	ULA2*D5011MB	A	993N	23-06-2025
	Amount	UoM	Unit type	ST ECOPACK Grade
	42.55	mg	Each	ECOPACK® 2
	Comment	ECOPACK® 2 is STMicroelectronics trade name for ROHS compliant device without Brominated and Chlorinated compound (900ppm) and without Antimony oxide flame retardant ( in each organic material)		

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
3	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable; if coating is used or other bulk termination	Tin (Sn), matte	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	4X4X1mm	24	No lead	
Comment	Package : B0KN VFQFPN 4X4X1 24L WETTABLE FLANKS DM00870342			

QueryList : RoHS Directive 2011/65/EU-July 2011 – Annex II amended by Directive 2015/863-April 2015	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	TRUE
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	FALSE
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	FALSE
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	FALSE
Exemption Id.	Description

QueryList : REACH-27th June 2024				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				TRUE
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	ULA2*D5011MB				6000000.0	1000016.4
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die or dies	M-011 Other inorganic materials	7.226	mg	supplier	die	Silicon (Si)	7440-21-3		7.108	mg	983670	167051
				supplier	metallization	Aluminium (Al)	7429-90-5		0.014	mg	1937	329
				supplier	metallization	Copper (Cu)	7440-50-8		0.047	mg	6504	1105
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.017	mg	2353	400
				supplier	Passivation	Silicon Nitride	12033-89-5		0.009	mg	1246	212
				supplier	Passivation	Silicon Oxide	7631-86-9		0.031	mg	4290	729
Leadframe_C194 Ag	Copper & its alloys	16.669	mg	Supplier	Alloy	Copper	7440-50-8		16.164	mg	969700	379888
					Alloy	Iron	7439-89-6		0.382	mg	22900	8971
					Alloy	Phosphorus	7723-14-0		0.005	mg	300	118
					Alloy	Zinc	7440-66-6		0.025	mg	1500	588
					coating	Silver	7440-22-4		0.093	mg	5600	2194
Glue -8600	M-011 Other inorganic materials	1.191	mg	Supplier	Glue	Silver >= 99.9 % Ag as powder	7440-22-4		0.971	mg	815000	22820
					Glue	[Octahydro-4,7-methano-1H-indenediy]bis(m	42594-17-2		0.071	mg	60000	1680
					Glue	exo-1,7,7-trimethylbicyclo[2.2.1]hept-2-yl met	7534-94-3		0.071	mg	60000	1680
					Glue	Isobornyl acrylate	5888-33-5		0.071	mg	60000	1680
					Glue	2-(3,4-Epoxy cyclohexyl)ethyltrimethoxysilane	3388-04-3		0.006	mg	5000	140
Bonding wire- Au wire	M-011 Other inorganic materials	0.128	mg	Supplier	Bonding wire	Au	7440-57-5		0.127	mg	992000	2976
					Bonding wire	Pt	7440-06-4		0.001	mg	6000	18
					Bonding wire	Pd	7440-05-3		0.000	mg	2000	6
Encapsulation - G700LTD	M-011 Other inorganic materials	15.677	mg	Supplier	Molding compound	Epoxy Resin	Proprietary		0.784	mg	50000	18422
					Molding compound	Phenol Resin	9003-35-4		0.423	mg	27000	9948
					Molding compound	Silica (Amorphous)A	60676-86-0		13.639	mg	870000	320536
					Molding compound	Silica (Amorphous)B	7631-86-9		0.784	mg	50000	18422
External plating-Tin	M-011 Other inorganic materials	1.659	mg	Supplier	Molding compound	Carbon Black	1333-86-4		0.047	mg	3000	1105
					External plating	Sn	7440-31-5		1.659	mg	1000000	39000